

Product Change Notification - KSRA-05DWWG372 [\(Printer Friendly\)](#)

Date:

14 Feb 2017

Product Category:

8-bit PIC Microcontrollers; USB Bridge

Notification subject:

CCB 2854: Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of 200K wafer technology available in 14L SOIC package at MMT assembly site

Notification text:
PCN Status:

Initial notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of 200K wafer technology available in 14L SOIC package at MMT assembly site using 95x155 mils lead frame paddle size

Pre Change:

Assembled at MMT using gold (Au) bond wire, 90X110 mils lead frame paddle size, spot LF plating and assembled in MTAI using Palladium coated copper (PdCu) bond wire, 95X155 mils lead frame paddle size, and Bare Cu LF surface

Post Change:

Assembled in MMT using palladium coated copper with gold flash (CuPdAu) bond wire, 95X155 mils lead frame paddle size, and Bare Cu LF surface

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	MMT	MTAI	MMT
Wire material	Au Wire	PdCu Wire	CuPdAu Wire

Die attach material	8390A	8390A	8390A
Molding compound material	G600V	G600V	G600V
Lead frame material	C194	C194	C194
Lead Frame Paddle Size	90x110 mils	95x155 mils	95x155 mils
LF Surface	Spot	Bare Cu	Bare Cu

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at MMT assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

April 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Time Table Summary:

	February 2017					→	April 2017				
	05	06	07	08	09		14	15	16	17	18
Workweek											
Initial PCN Issue Date			X								
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

February 14, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-05DWWG372_Affected CPN.pdf](#)

[PCN_KSRA-05DWWG372_Qual Plan.pdf](#)

[PCN_KSRA-05DWWG372_Affected CPN.xlsx](#)

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